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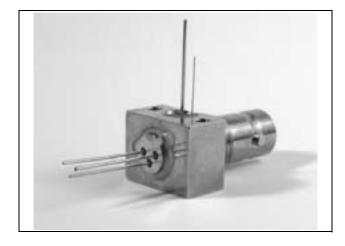
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125 MHz Full Duplex Module (1320 nm Tx, 820 nm Rx)

Data Sheet

March 2004



Features

- Full Duplex Communication Over One Fiber
- Dual Wavelengths 820/1300 nm
- · Very Small Size
- Very Low Internal Crosstalk
- · Packaged in Industry-Standard ST® Receptacle
- Designed for 62.5/125 µm Fiber

Ordering Information

MF699 ST-duplex package

-40°C to +85°C

Applications

- Ethernet 10 or 100 Mbps
- Token Ring
- Fibre Channel 266 Mbps
- FDDI
- ATM-SDH/SONET 155 Mbps
- Intra-Office Telecom
- WDM Applications

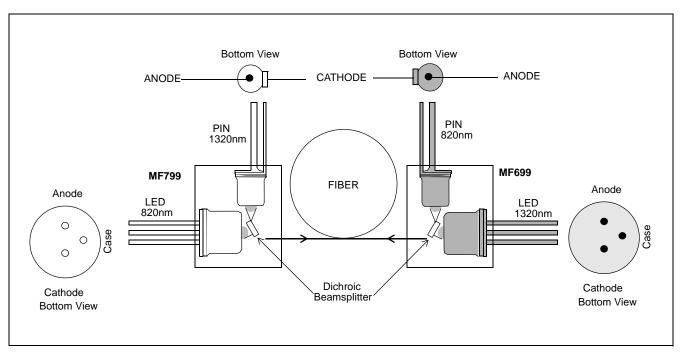


Figure 1 - MF699 Functional Diagram

Description

Used in combination with the MF799, the MF699 Duplex Device is designed for WDM (Wavelength Division Multiplex), Datacom, Video Links, or Intra-Office Telecom Applications. It emits optical power at 1320 nm and detects incoming optical power at 820 nm, allowing full Duplex Communication over one single fiber.

The MF699 uses dichroic (wavelength-selective) beamsplitters for maximum power budget and minimum crosstalk. Minimum internal crosstalk is achieved by the use of wavelength-selective detectors. The long wavelength path meets requirements for FDDI (ANSI X3T9.5) and ATM 155 Mbps.

The MF699 is designed for multi-mode fiber and optimized for 62.5/125 µm fiber.

Absolute Maximum Ratings

Parameter	Symbol	Limit
Storage Temperature	T _{stg}	-55 to +125°C
Operating Temperature (Figure 3)	T_{op}	-40 to +85°C
LED Power Dissipation (Figure 3)	P_{tot}	160 mW
LED Continuous Forward Current (≤10 kHz)	l _F	80 mA
LED Peak Forward Current (duty cycle ≤50%, f≥1 MHz)	I _{FRM}	130 mA
LED Reverse Voltage	V_{RL}	0.5 V
PIN Reverse Voltage	V_{RP}	20 V
Soldering Temperature (2 mm from the case for 10 sec)	T _{sld}	260°C

LED Optical & Electrical Characteristics (Case Temperature -25 to +70°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Conditions
Fiber-Coupled Power (Figure 2)	P_{fiber}	-20.5			dBm	I _{Peak} = 60 mA (Note 1, 2)
Rise & Fall Time (10 - 90% no bias)	t _{r'tf}		2.5	3.5	ns	I _F = 60 mA (Note 2)
Bandwidth (3 dB _{el})	f _C		125		MHz	I _F = 60 mA (Note 2)
Peak Wavelength	λ_{p}		1320		nm	I _F = 60 mA
Spectral Width (FWHM)	Δλ		135	180	nm	I _F = 60 mA
Forward Voltage (Figure 4)	V_{F}		1.3	1.65	V	I _F = 60 mA
Reverse Current	I _R			100	μΑ	V _R = 1 V
Capacitance	С		200		pF	$V_R = 0V, f = 1 MHz$

Note 1: Average power at 10 MHz/50% duty cycle. Measured at the exit of 100m of fiber.

Note 2: $62.5/125 \mu m$ graded index fiber (NA = 0.275).

PIN Optical & Electrical Characteristics (Case Temperature -25 to +70°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Conditions
Responsivity (Figure 5)	R	0.25			A/W	$V_R = 5 V \lambda = 820$ nm (Note 1)
Bandwidth	f _c	500			MHz	$VR = 5 V R_L = 50 \Omega$ (Note 1)
Capacitance (Figure 6)	С		1		pF	$V_R = 5V f = 1 MHz$
Dark Current	I _d			3 50	nA	$T_{Case} = 25^{\circ}C$ $T_{Case} = 70^{\circ}C$ $V_{R} = 5 \text{ V I}_{LED} = 0 \text{ mA}$
Crosstalk Current	I _{Cr}		3		nA	V _R = 5 V I _{LED} = 60 mA (Note 2)

Note 1: $62.5/125 \mu m$ graded index fiber (NA = 0.275).

Note 2: Internal crosstalk with ceramic ferrule inserted but no power from the fiber. Total Current = dark current + crosstalk current.

LED Thermal Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Units
Thermal Resistance - Infinite Heat Sink	R _{thjc}			200	°C/W
Thermal Resistance - On PC Board	R _{thjb}			300	°C/W
Temperature Coefficient - Optical Power	dP/dT _j		-0.75		%/°C
Temperature Coefficient - Wavelength	$d\lambda/dT_{j}$		0.45		nm/°C

PIN Thermal Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Units
Temperature Coefficient - Dark Current	dl _d /dT _j		5		%/°C
Temperature Coefficient - Crosstalk Current	dl _{Cr} /dT _j		-0.75		%/°C

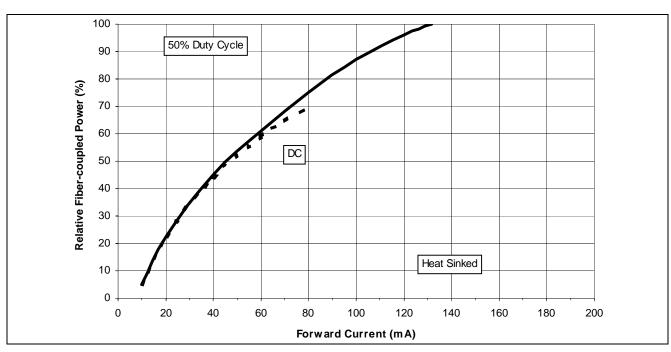


Figure 2 - Relative Fiber-Coupled Power vs Forward Current

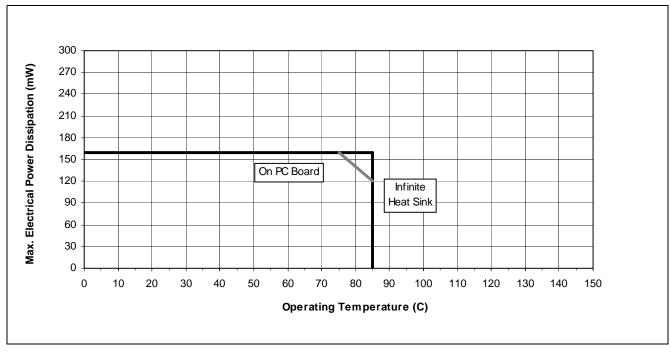


Figure 3 - Max. Electrical Power Dissipation vs Operating Temperature

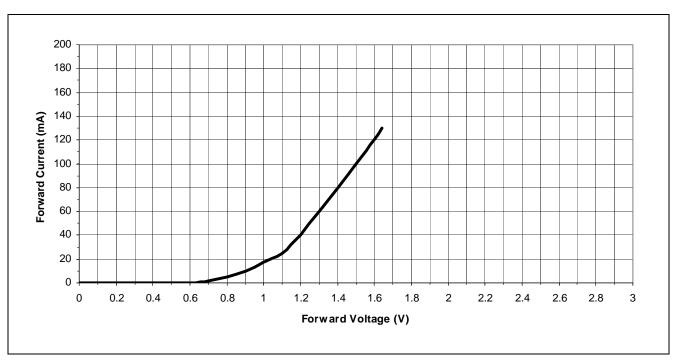


Figure 4 - Forward Current vs Forward Voltage

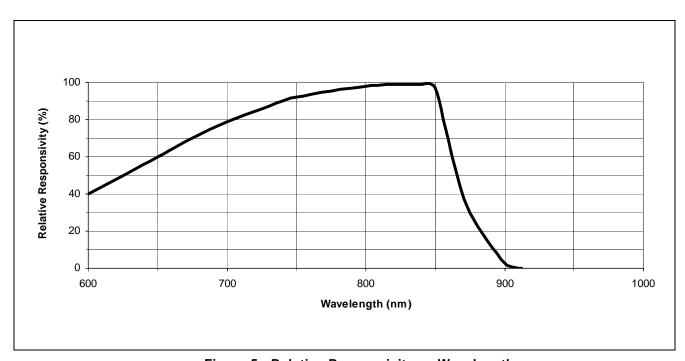


Figure 5 - Relative Responsivity vs Wavelength

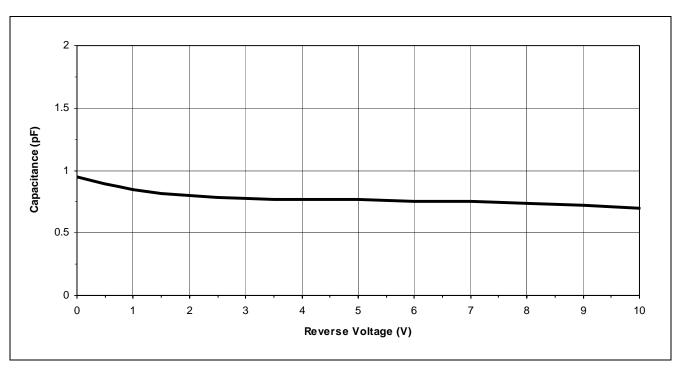


Figure 6 - Capacitance vs Reverse Voltage

FRONT VIEW (2:1) **TOP VIEW BOTTOM VIEW** -2-56 UNC-2B, THRU (2x) Ø2,501 +0,008 lacksquare12,7 Α Slot side Ø7 3,85 +0 -0,05 $13,5 \pm 0,5$ 9,6 13 ± 1 6,65 0,2 9,5 SIDE VIEW "B" 13,35 Ø2 B 16,2 Component * MATING FERRULE (Not included) Ø2,501 ⁺⁰ _{-0,004} -3/8"-32 UNEF 0,006 Component * NOTES:-3,35 $7,89 \pm 0,03$ 1. All dimensions in mm. FIBER END 20,1 2. General tol. ISO-2768-mK * For details of the component, see separate data sheet and/or package drawing. Projection Method Dackage code

© Zariink	Semiconal	JCTOF 2002.	All rights r	eservea.			Package code TH
ISSUE	2	3				Previous package codes	Drawing type
ACN	102557 rev2	102557 rev3			EXECUTE ZARLINK	ST-D	Package Outline drawing for Duplex ST Receptacle
DATE	06-APR-04	10-JUN-04			SEMICONDUCTOR		Title
APPRD.	MD/MA	MD/MA					102557



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